SDLS040

TRIPLE 3-INPUT POSITIVE-NAND GATES WITH OPEN-COLLECTOR OUTPUTS

DECEMBER 1983—REVISED MARCH 1988

- **Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs**
- **Dependable Texas Instruments Quality and Reliability**

description

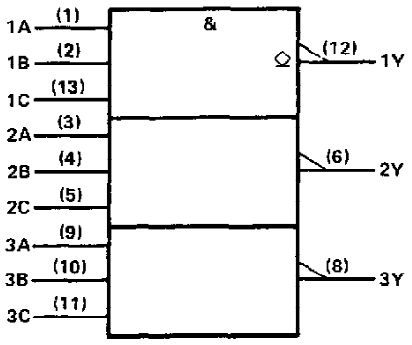
These devices contain three independent 3-input NAND gates with open-collector outputs. The open-collector outputs require pull-up resistors to perform correctly. They may be connected to other open-collector outputs to implement active-low wired-OR or active-high wired-AND functions. Open-collector devices are often used to generate higher V_{OH} levels.

The SN5412 and SN54LS12 are characterized for operation over the full military temperature range of −55°C to 125°C. The SN7412 and SN74LS12 are characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each gate)

INPUTS			OUTPUT
A	B	C	Y
H	H	H	L
L	X	X	H
X	L	X	H
X	X	L	H

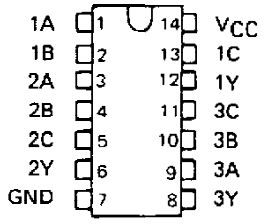
logic symbol†



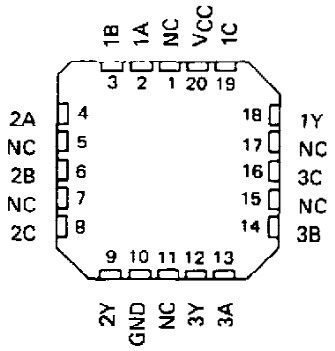
† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

SN5412, SN54LS12 . . . J OR W PACKAGE
SN7412 . . . N PACKAGE
SN74LS12 . . . D OR N PACKAGE
(TOP VIEW)

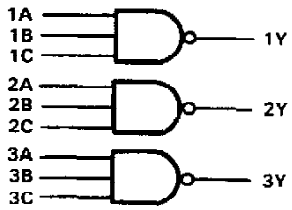


SN54LS12 . . . FK PACKAGE
(TOP VIEW)



NC—No internal connection

logic diagram (positive logic)



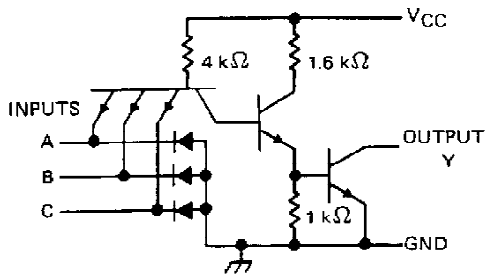
$Y = \overline{A \cdot B \cdot C}$ or

$Y = \overline{A} + \overline{B} + \overline{C}$

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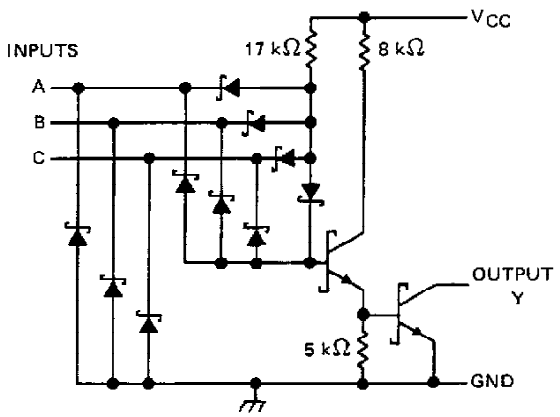
schematics (each gate)

'12



Resistor values shown are nominal.

'LS12



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage: '12 . . . . . 5.5 V
'LS12 . . . . . 7 V
Off-state output voltage . . . . . 7 V
Operating free-air temperature: SN54' . . . . . −55°C to 125°C
SN74' . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN5412			SN7412			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
V_{OH}	High-level output voltage			5.5			5.5	V
I_{OL}	Low-level output current			16			16	mA
T_A	Operating free-air temperature	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN5412			SN7412			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	V_{CC} = MIN, I_I = −12 mA			−1.5			−1.5	V
I_{OH}	V_{CC} = MIN, V_{IL} = 0.8 V, V_{OH} = 5.5 V						0.25	mA
	V_{CC} = MIN, V_{IL} = 0.7 V, V_{OH} = 5.5 V			0.25				
V_{OL}	V_{CC} = MIN, V_{IH} = 2 V, I_{OL} = 16 mA		0.2	0.4		0.2	0.4	V
I_I	V_{CC} = MAX, V_I = 5.5 V			1			1	mA
I_{IH}	V_{CC} = MAX, V_I = 2.4 V			40			40	μA
I_{IL}	V_{CC} = MAX, V_I = 0.4 V			−1.6			−1.6	mA
I_{CCH}	V_{CC} = MAX, V_I = 0		3	6		3	6	mA
I_{CCL}	V_{CC} = MAX, V_I = 4.5 V		9	16.5		9	16.5	mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡All typical values are at V_{CC} = 5 V, T_A = 25°C.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	A, B or C	Y	R_L = 4 kΩ, C_L = 15 pF		35	45	ns
t_{PHL}			R_L = 400 Ω, C_L = 15 pF		8	15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

recommended operating conditions

	SN54LS12			SN74LS12			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH} High-level input voltage	2			2			V
V_{IL} Low-level input voltage			0.7			0.8	V
V_{OH} High-level output voltage			5.5			5.5	V
I_{OL} Low-level output current			4			8	mA
T_A Operating free-air temperature	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54LS12			SN74LS12			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	V_{CC} = MIN, I_I = −18 mA			−1.5			−1.5	V
I_{OH}	V_{CC} = MIN, V_{IL} = MAX, V_{OH} = 5.5 V			0.1			0.1	mA
V_{OL}	V_{CC} = MIN, V_{IH} = 2 V, I_{OL} = 4 mA		0.25	0.4		0.25	0.4	V
	V_{CC} = MIN, V_{IH} = 2 V, I_{OL} = 8 mA					0.35	0.5	
I_I	V_{CC} = MAX, V_I = 7 V			0.1			0.1	mA
I_{IH}	V_{CC} = MAX, V_I = 2.7 V			20			20	μA
I_{IL}	V_{CC} = MAX, V_I = 0.4 V			−0.4			−0.4	mA
I_{CCH}	V_{CC} = MAX, V_I = 0		0.7	1.4		0.7	1.4	mA
I_{CCL}	V_{CC} = MAX, V_I = 4.5 V		1.8	3.3		1.8	3.3	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	A, B or C	Y	R_L = 2 kΩ, C_L = 15 pF		17	32	ns
t_{PHL}					15	28	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN5412J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	-55 to 125		
SN7412N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN7412N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74LS12D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		
SN74LS12D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		
SN74LS12DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		
SN74LS12DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		
SN74LS12N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74LS12N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74LS12N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74LS12N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SNJ5412J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	-55 to 125		
SNJ5412J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	-55 to 125		
SNJ5412W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI	-55 to 125		
SNJ5412W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI	-55 to 125		

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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OTHER QUALIFIED VERSIONS OF SN5412, SN7412 :

- Catalog: SN7412
- Military: SN5412

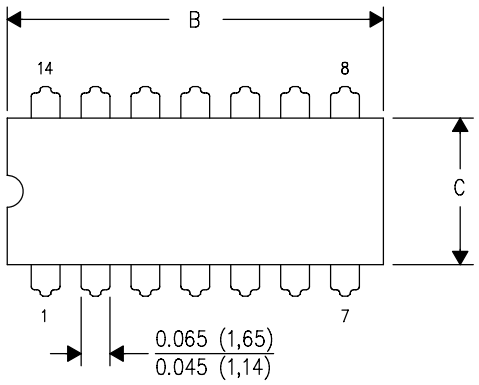
NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

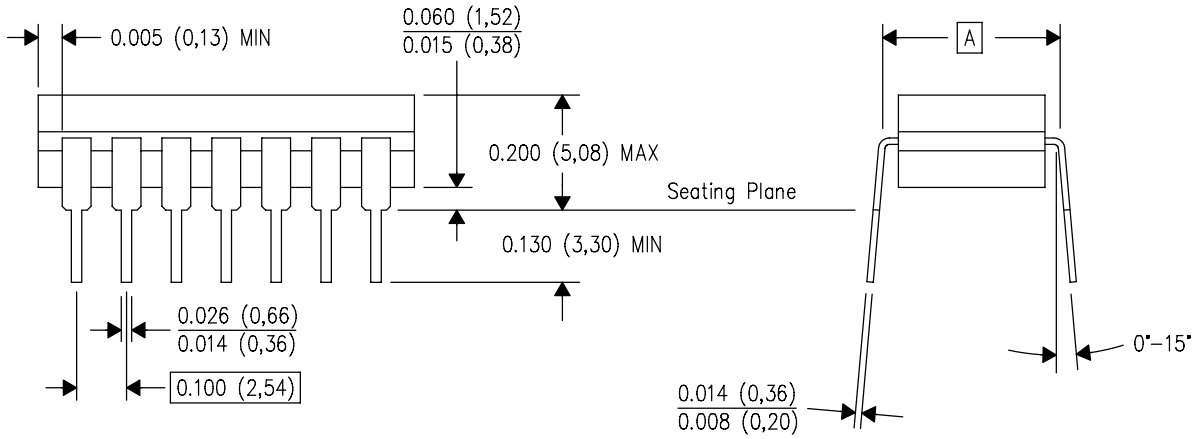
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



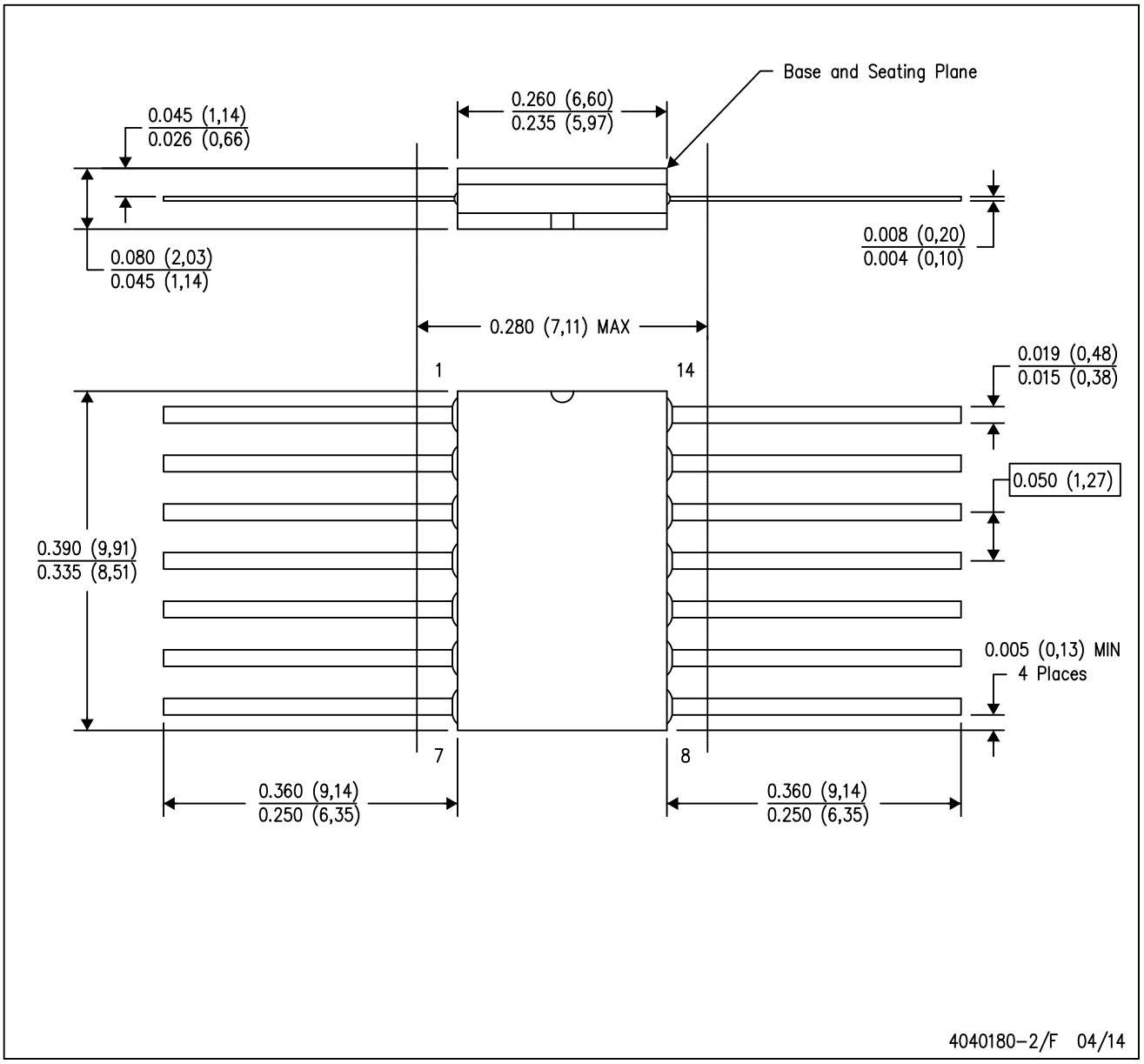
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

W (R–GDFP–F14) CERAMIC DUAL FLATPACK

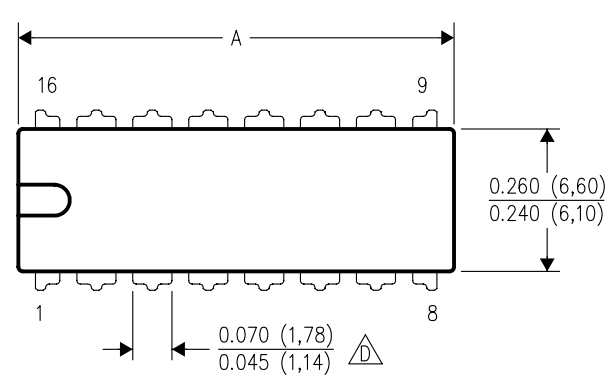


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1–F14

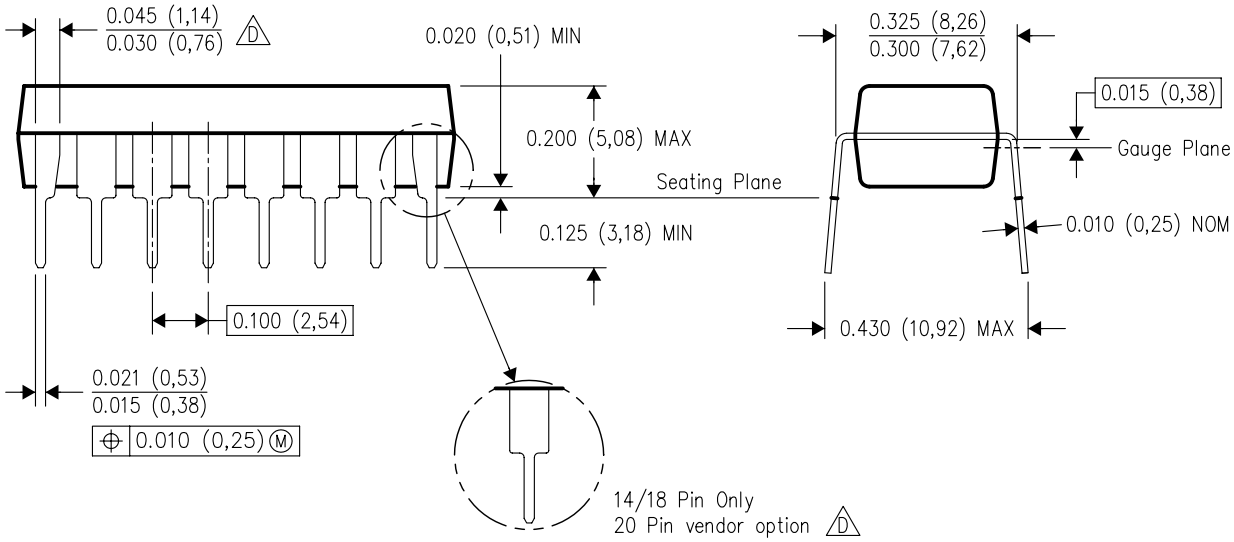
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



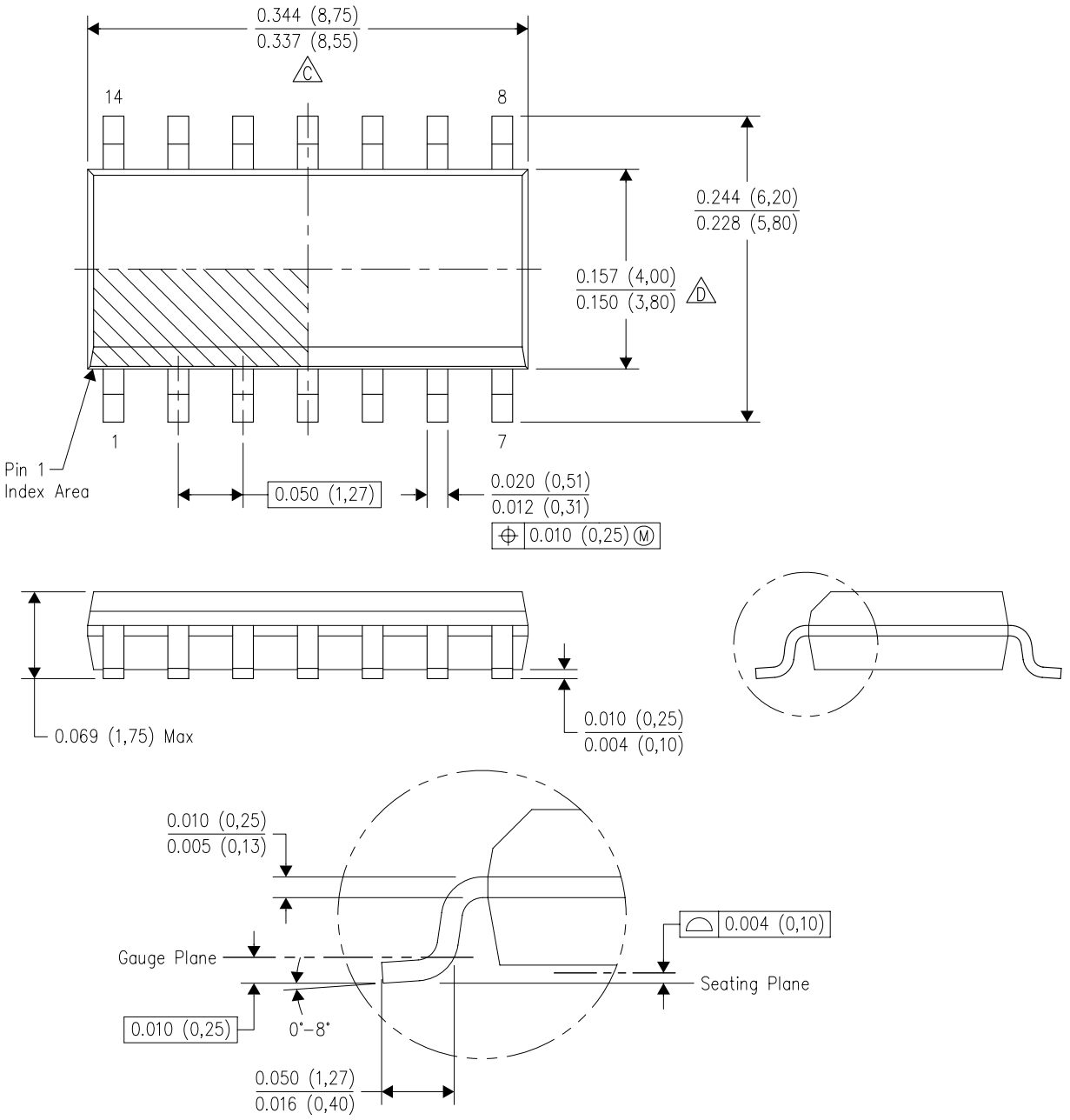
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R–PDSO–G14) PLASTIC SMALL OUTLINE



4040047–5/M 06/11

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AB.

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